

<b>Electronic Patent Application Fee Transmittal</b>				
<b>Application Number:</b>	10706977			
<b>Filing Date:</b>	14-Nov-2003			
<b>Title of Invention:</b>	Wafer processing apparatus having dust proof function			
<b>First Named Inventor/Applicant Name:</b>	Tsutomu Okabe			
<b>Filer:</b>	Marvin Jay Spivak/Maritza Ulloa			
<b>Attorney Docket Number:</b>	245166US3CIP			
Filed as Large Entity				
<b>Utility under 35 USC 111(a) Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Statutory disclaimer	1814	1	140	140
<b>Total in USD (\$)</b>				<b>140</b>